

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

CLAIMS 1 - 10 (CANCELLED).

11. (CURRENTLY AMENDED) A thermally enhanced printed circuit (PC) wiring board to which ball grid integrated circuit packages are to be mounted thereon comprising a relatively thin, conductive metal core layer having a thickness in the range of 5 - 15 mils and
5 having oppositely facing surfaces and one or more holes in the metal core at each of a plurality of through-core via sites,

[[a]] first and second thin rigidifying non-conductive laminate sheet, each having a thickness within the range of 1.5 to 3 mils, attached to said oppositely facing surfaces, respectively,
10 wherein at least one of said nonconductive laminate sheets has a glass fiber ingredient which allows for structural enhancement against thermal expansion coefficient mismatch between said metal core and said one of said nonconductive laminate sheets, and

at least one conductive circuit pattern on at least one of
15 said thin rigidifying non-conductive laminate sheets and a plurality of vias thereon.

12. (ORIGINAL) The PC wiring board defined in Claim 11 including a plurality of vias made by plating build-up and connecting to the core from both the top and bottom sides thereof.

Claim 13 (CANCELLED).

14. (CURRENTLY AMENDED) The PC wiring board defined in ~~Claim 13~~ Claim 11 including one or more additional non-conductive ~~and~~ conductive layers thereon having a thickness within the range of 1.5 to 3 mils.

15. (ORIGINAL) The PC wiring board defined in Claim 11 including a plurality of vias selected from Type 1, Type 2 or Type 3 vias as defined herein.

CLAIM 16 (CANCELLED).

17. (CURRENTLY AMENDED) A thermally enhanced printed circuit (PC) wiring board for mounting ball grid integrated circuit packages thereon comprising:

a conductive metal core layer in the range of 5 - 15 mils thick and having oppositely facing surfaces and one or more holes in the metal core at each of a plurality of through-core via sites,

[[a]] first and second thin rigidifying non-conductive fiberglass laminate sheets having a thickness in the range of 1.5

to mils attached to said oppositely facing surfaces of said
10 conductive metal core layer, respectively, wherein one of said
nonconductive laminate sheets has a glass fiber ingredient which
allows for structural enhancement against thermal expansion
coefficient mismatch between said metal core and said one of said
nonconductive laminate sheets,

15 at least one conductive circuit pattern on at least one of
said thin rigidifying non-conductive sheets, and

a plurality of vias selected from type 1, type 2 or type 3
vias made by plating build-up and connecting to the conductive
metal core selectively from the top and bottom sides thereof,
20 respectively.

18. (PREVIOUSLY PRESENTED) A thermally enhanced printed
circuit (PC) wiring board and at least one ball grid integrated
circuit package mounted thereon, said PC wiring board comprising:

a conductive metal core layer in the range of 5 - 15 mils
5 thick and having oppositely facing surfaces and one or more holes
in the metal core at each of a plurality of through-core via sites,

[[a]] first and second thin rigidifying non-conductive
fiberglass laminate sheets having a thickness within the range of
1.5 to 3 mils attached to said oppositely facing surfaces of said
10 conductive metal core layer, respectively, wherein one of said
nonconductive laminate sheets has a glass fiber ingredient which
allows for structural enhancement against thermal expansion

coefficient mismatch between said metal core and said one of said nonconductive laminate sheets,

15 at least one conductive circuit pattern on at least one of said thin rigidifying non-conductive sheets, and

 a plurality of vias selected from type 1, type 2 or type 3 vias made by plating build-up and connecting to the core selectively from the top and bottom sides thereof, respectively.